ABSOCIATION CONNECTING LECTRONICS INDUSTRIES® Material Comp © Copyright 2005. I international and Pai	PC. Bannockł	ourn, Illinois, A	Il rights reserved untions.	under both	This docume level parts, t	ent is a declaration entries the declaration entries and t	on of the su	bstances v all lower	vithin the manufactu level materials for v	urer listed which the	item. Note: manufacture	if the item is an as er has engineering	sembly with lower responsibility.	
				Form Type Distribute					rials and N	ials and Mfg Information				
Supplier Information														
Company name* Com			Company unique ID			Unique ID Authority				Respon	Response Date*			
onsemi										2024-0	2024-04-25			
Contact Name Title - Contact			t			Phone - Contact*				Email	Email - Contact*			
Product-Env-Stewards Product En			Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - Rep			Representative			Phone - Representative*				Email	Email - Representative*			
Product-Env-Stewards Product			oduct Enviro Compliance			NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Item Number	Mfr Item	n Number	Mfr Item Name			Effective Date	Version	М	Manufacturing Site		Weight*	UOM	Unit Type	
	MOC30	OC3083SR2VM 6PW ZC TRIA		C T&R VDE		2024-04-25		T	ТНН		464.903	mg	Each	
Manufacturing Proccess Informa	tion												·	
Terminal Plating / Grid Array M	aterial 7	Ferminal Base	lloy J-STD-020 MSL Ratin		L Rating	Peak Proce	rocess Body Temperatu		are Max Time at Peak Tempera		ature Num	nber of Reflow Cyc	les	
Matte Tin (Sn) - annealed CU Alloy		CU Alloy		1		260	260 C		30 seco		seconds 3			
Comments														
level 1 - maximum time at peak temperatu	ure during so	ldering is 10-3	0 seconds											
For more information regarding material	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chror	bHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead b), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl thalate (BBP), Dibutyl phthalate (DBP), Disobutyl phthalate (DIBP).									
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe y others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and cc for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	on above	Supplier Acceptance	* Accepted							
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the						
Supplier Digital Signature Ra	stislav Drska	Le									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Coupling Gel	0.4	mg	Supplier	Dimethyl Cyclosiloxanes	69430-24-6		0.04	mg
			Supplier	Trimethoxy(methyl)silane (C4H12O3Si)	1185-55-3		0.36	mg
Die	5.13	mg	Supplier	Silicon (Si)	7440-21-3		5.13	mg
Die Attach	0.3	mg	Supplier	Silver (Ag)	7440-22-4		0.225	mg
			Supplier	Phenolic Resin-2	54208-63-8		0.075	mg
Lead Frame 1	101.703	mg	Supplier	Silver (Ag)	7440-22-4		0.407	mg
			Supplier	Zinc (Zn)	7440-66-6		0.203	mg
			Supplier	Iron (Fe)	7439-89-6		2.64	mg
			Supplier	Copper (Cu)	7440-50-8		98.3	mg
			Supplier	Phosphorus (P)	7723-14-0		0.153	mg
Mold Compound-White	327.22	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		81.805	mg
			В	Brominated Bisphenol A Diglycidyl Ether	40039-93-8		9.8166	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		44.1747	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		9.8166	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		163.61	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		17.9971	mg
Plating	28.5	mg	Supplier	Tin (Sn)	7440-31-5		28.5	mg
Wire Bond - Au	1.65	mg	Supplier	Gold (Au)	7440-57-5		1.65	mg